



TFW

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Attn: OIPE

Masakazu SATO et al.

Group Art Unit: 2863

Application No.: 10/517,655

Docket No.: 122035

Filed: December 13, 2004

For: METHOD OF EVALUATING SHAPE OF SEMICONDUCTOR WAFER AND
APPARATUS FOR EVALUATING SHAPE OF SEMICONDUCTOR WAFER

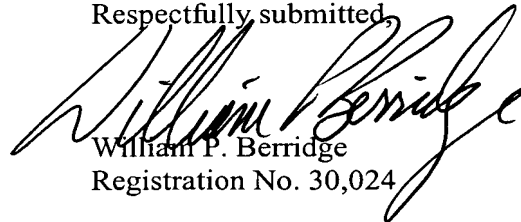
REQUEST FOR CORRECTION OF PALM RECORDS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records. A Supplemental Application Data Sheet is attached.

Respectfully submitted,



William P. Berridge
Registration No. 30,024

WPB:cab

Date: October 16, 2006

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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>

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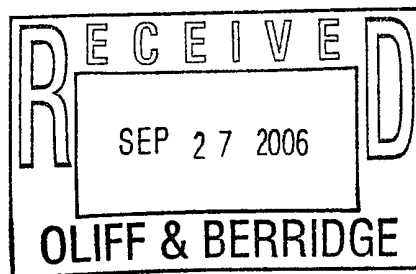
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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/517,655	12/13/2004	2863	6600	122035	8	132	2

25944
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 ALEXANDRIA, VA 22320



CONFIRMATION NO. 7281

CORRECTED FILING RECEIPT



OC000000020571957

Date Mailed: 09/25/2006

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Masakazu Sato, Fukushima, JAPAN;
 Masato Onishi, Fukushima, JAPAN;

Assignment For Published Patent Application

SHIN-ETSU HANDOTAI ~~CO LTD~~, ^{Tokyo} Chiyoda-ku, JAPAN
 CO., LTD.

Power of Attorney: The patent practitioners associated with Customer Number 25944.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP03/07320 06/10/2003

Foreign Applications

JAPAN 2002173268 06/13/2002

If Required, Foreign Filing License Granted: 09/25/2006

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US10/517,655**

Projected Publication Date: Not Applicable

Non-Publication Request: No

Early Publication Request: No

Title

METHOD OF EVALUATING SHAPE OF SEMINCONDUCTOR WAFER AND APPARATUS FOR
EVALUATING SHAPE OF SEMINCONDUCTOR WAFER

Preliminary Class

702

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AHA



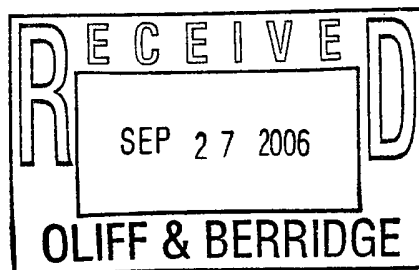
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**Supplemental Application Data Sheet****Applicant Information**

Applicant Authority type::	Inventor
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Family Name::	ONISHI
City of Residence::	Fukushima
Country of Residence::	Japan

Correspondence Information

Correspondence Customer Number::	25944
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Application Information

Application Type::	National Phase
Subject Matter::	Utility
CD-ROM or CD-R::	None
Title::	METHOD OF EVALUATING SHAPE OF SEMICONDUCTOR WAFER AND APPARATUS FOR EVALUATING SHAPE OF SEMICONDUCTOR WAFER
Attorney Docket Number::	122035
Total Drawing Sheets::	8
Small Entity::	No



Representative Information

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Domestic Priority Information			
Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application is a	National Stage of	PCT/JP03/07320	06/10/2003
Foreign Priority Information			
Country::	Application Number::	Filing Date::	Priority Claimed::
Japan	2002-173268	06/13/2002	Yes
Assignee Information			
Assignee Name::		SHIN-ETSU HANDOTAI CO., LTD.	
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